SCBS1450 - MAY 1992 - REVISED SEPTEMBER 2003

- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- I_{off} and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

SN54LVTH16374... WD PACKAGE SN74LVTH16374... DGG OR DL PACKAGE (TOP VIEW)

		_	_	1
1OE	1	\cup	48]1CLK
1Q1	2		47]1D1
1Q2	3		46]1D2
GND	4		45	GND
1Q3	5		44] 1D3
1Q4	6		43]1D4
V _{CC}	7		42]v _{cc}
1Q5	8] 1D5
1Q6	9		40] 1D6
GND	10		39	GND
1Q7	11		38] 1D7
1Q8	12		37] 1D8
2Q1	13		36]2D1
2Q2	14		35	2D2
GND	15		34	GND
2Q3	16		33]2D3
2Q4	17		32]2D4
V _{CC}	18		31]v _{cc}
2Q5	19		30]2D5
2Q6	20		29]2D6
GND	21		28]GND
2Q7	22		27]2D7
2Q8			26]2D8
2 <mark>OE</mark>	24		25]2CLK
	_			

description/ordering information

The 'LVTH16374 devices are 16-bit edge-triggered D-type flip-flops with 3-state outputs designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment. These devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	CCOD DI	Tube	SN74LVTH16374DL	1)/TU40274
	SSOP – DL	Tape and reel	SN74LVTH16374DLR	LVTH16374
-40°C to 85°C	TSSOP – DGG	Tape and reel	SN74LVTH16374DGGR	LVTH16374
	VFBGA – GQL	Town and soul	SN74LVTH16374GQLR	11074
	VFBGA – ZQL (Pb-free)	Tape and reel	SN74LVTH16374ZQLR	LL374
-55°C to 125°C	CFP – WD	Tube	SNJ54LVTH16374WD	SNJ54LVTH16374WD

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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description/ordering information (continued)

These devices can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK), the Q outputs of the flip-flop take on the logic levels set up at the data (D) inputs.

A buffered output-enable (OE) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.

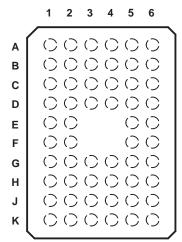
OE does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for hot-insertion applications using Ioff and power-up 3-state. The Ioff circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

GQL OR ZQL PACKAGE (TOP VIEW)



terminal assignments

	1	2	3	4	5	6
Α	1OE	NC	NC	NC	NC	1CLK
В	1Q2	1Q1	GND	GND	1D1	1D2
С	1Q4	1Q3	Vcc	Vcc	1D3	1D4
D	1Q6	1Q5	GND	GND	1D5	1D6
Е	1Q8	1Q7			1D7	1D8
F	2Q1	2Q2			2D2	2D1
G	2Q3	2Q4	GND	GND	2D4	2D3
Н	2Q5	2Q6	Vcc	Vcc	2D6	2D5
J	2Q7	2Q8	GND	GND	2D8	2D7
K	2OE	NC	NC	NC	NC	2CLK
-						

NC - No internal connection

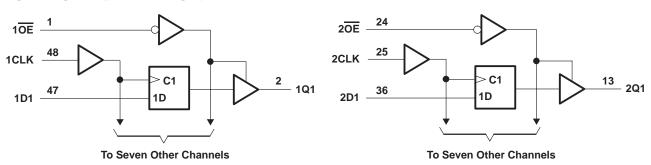
FUNCTION TABLE (each flip-flop)

	INPUTS						
OE	CLK	D	Q				
L	\uparrow	Н	Н				
L	\uparrow	L	L				
L	H or L	Χ	Q_0				
Н	X	Χ	Z				



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logic diagram (positive logic)



Pin numbers shown are for the DGG, DL, and WD packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, V _O (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Current into any output in the low state, I _O : SN54LVTH16374	96 mA
SN74LVTH16374	
Current into any output in the high state, IO (see Note 2): SN54LVTH16374	48 mA
SN74LVTH16374	64 mA
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 3): DGG package	70°C/W
DL package	
GQL/ZQL package	42°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

- 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			SN54LVT	H16374	SN74LVT	H16374	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2.7	3.6	2.7	3.6	V
VIH	High-level input voltage				2		V
VIL	Low-level input voltage		0.8		8.0	V	
VI	Input voltage			5.5		5.5	V
loн	High-level output current			-24		-32	mA
loL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200		200		μs/V
TA	Operating free-air temperature	_	-55	125	-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAD 411				SN5	SN54LVTH16374			SN74LVTH16374			
PAI	RAMETER	TEST CO	ONDITIONS	MIN		MAX	MIN	TYP†	MAX	UNIT	
VIK		$V_{CC} = 2.7 \text{ V},$	I _I = -18 mA			-1.2			-1.2	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$	$I_{OH} = -100 \mu A$	V _{CC} -0	.2		V _{CC} -0	.2			
\/ - · ·		$V_{CC} = 2.7 \text{ V},$	$I_{OH} = -8 \text{ mA}$ 2.4			2.4			V		
VOH		Va = - 2 V	$I_{OH} = -24 \text{ mA}$	2						V	
		V _{CC} = 3 V	$I_{OH} = -32 \text{ mA}$				2				
		\/== - 2.7.\/	$I_{OL} = 100 \mu A$			0.2			0.2		
		V _{CC} = 2.7 V	I _{OL} = 24 mA			0.5			0.5		
\/~·			$I_{OL} = 16 \text{ mA}$			0.4			0.4	V	
VOL		\\\\\\\	$I_{OL} = 32 \text{ mA}$			0.5			0.5	V	
		VCC = 3 V	$I_{OL} = 48 \text{ mA}$			0.55					
			I _{OL} = 64 mA						0.55		
		$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5 V			10			10		
1.	Control inputs	$V_{CC} = 3.6 \text{ V},$	$V_I = V_{CC}$ or GND			±1			±1		
I _I	Data innuta	V 26V	VI = VCC			1			1	μΑ	
	Data inputs	V _{CC} = 3.6 V	V _I = 0		-5		-5				
l _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V						±100	μΑ	
		V 0.V	V _I = 0.8 V	75			75				
l _l (hold)	Data inputs	VCC = 3 V	V _I = 2 V	-75			-75			μΑ	
		$V_{CC} = 3.6 V^{\ddagger}$,	$V_{I} = 0 \text{ to } 3.6 \text{ V}$						±500		
lozh		$V_{CC} = 3.6 \text{ V},$	V _O = 3 V			5			5	μΑ	
lozL		$V_{CC} = 3.6 \text{ V},$	$V_0 = 0.5 V$			-5			- 5	μΑ	
I _{OZPU}		$\frac{V_{CC}}{OE} = 0$ to 1.5 V, $V_{O} = 0$	0.5 V to 3 V,			±100*			±100	μΑ	
IOZPD		$\frac{\text{VCC}}{\text{OE}} = 1.5 \text{ V to 0, VO} = 0$	0.5 V to 3 V,			±100*			±100	μΑ	
		V _{CC} = 3.6 V,	Outputs high			0.19			0.19		
Icc		$I_{O} = 0$,	Outputs low			5			5	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled			0.19			0.19	1	
ΔlCC§		V _{CC} = 3 V to 3.6 V, On Other inputs at V _{CC} or			_	0.2		_	0.2	mA	
Ci		V _I = 3 V or 0			3			3		pF	
Со		$V_O = 3 \text{ V or } 0$			9			9		pF	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level, rather than VCC or GND.

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			SN54LVTH16374			SN74LVTH16374					
			V _{CC} =	3.3 V 3 V	VCC =	2.7 V	V _{CC} =	= 3.3 3 V	VCC =	2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency			160		160		160		160	MHz
t _W	Pulse duration, CLK high or low		3		3		3		3		ns
t _{su}	Setup time, data before CLK↑	High or low	2.9		3.3		1.8		2		ns
th	Hold time, data after CLK↑	High or low	0.8		0.2		0.8		0.1		ns

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

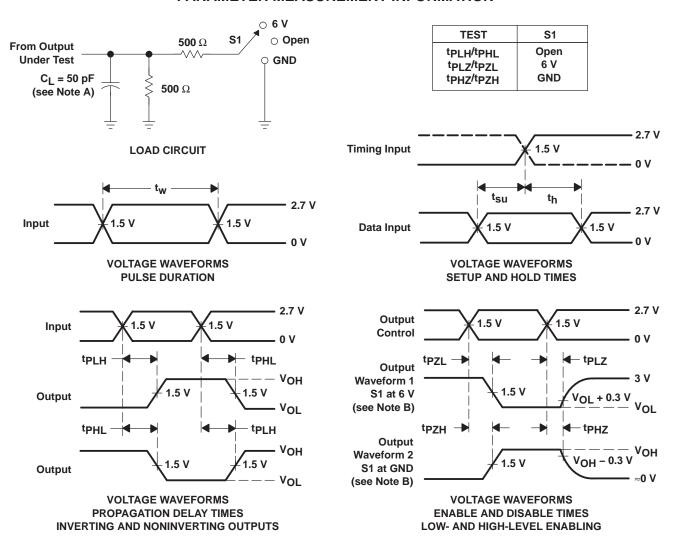
		5	SN54LVTH16374			SN74LVTH16374						
PARAMETER	FROM (INPUT)		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX	
f _{max}			160		160		160			160		MHz
t _{PLH}	CL K	0	1.4	5.6		6.2	1.9	3	4.5		5.2	
t _{PHL}	CLK	Q	1.7	4.8		5	2.1	2.9	4		4.2	ns
^t PZH	ŌE	0	1	5.6		6.4	1.5	2.8	4.5		5.4	
t _{PZL}	OE	Q	1.4	5.5		6.2	1.5	2.8	4.4		5	ns
^t PHZ	ŌĒ	Q	1	6.4		6.9	2.4	3.5	5		5.4	ns
^t PLZ	OL .	Q	1.7	5		5.2	2	3.2	4.6		4.8	115
tsk(o)						·	·		0.5			ns

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50~\Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

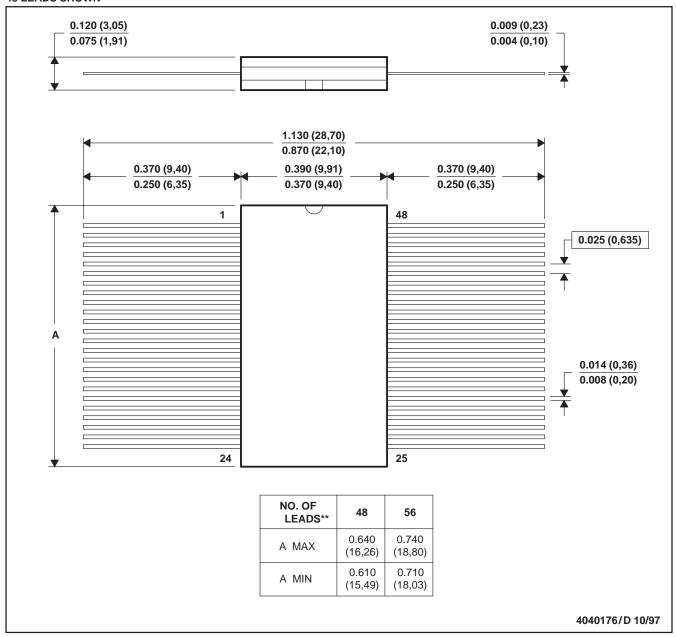
Figure 1. Load Circuit and Voltage Waveforms



WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

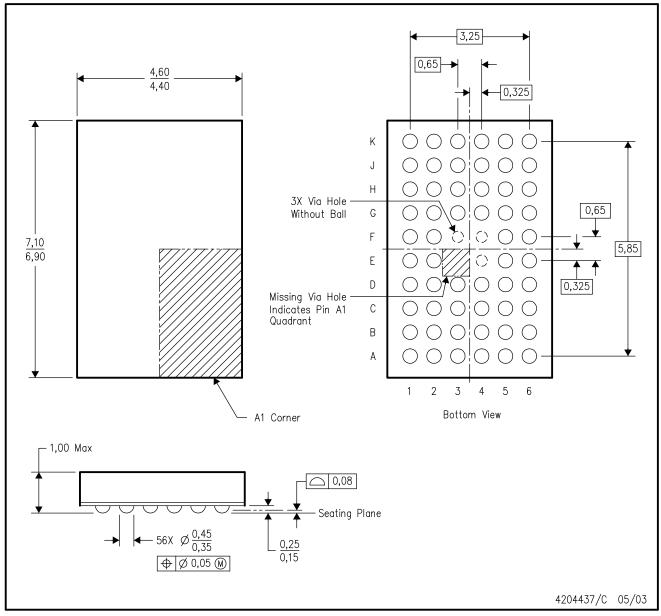
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

GDFP1-F56 and JEDEC MO-146AB



ZQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES:

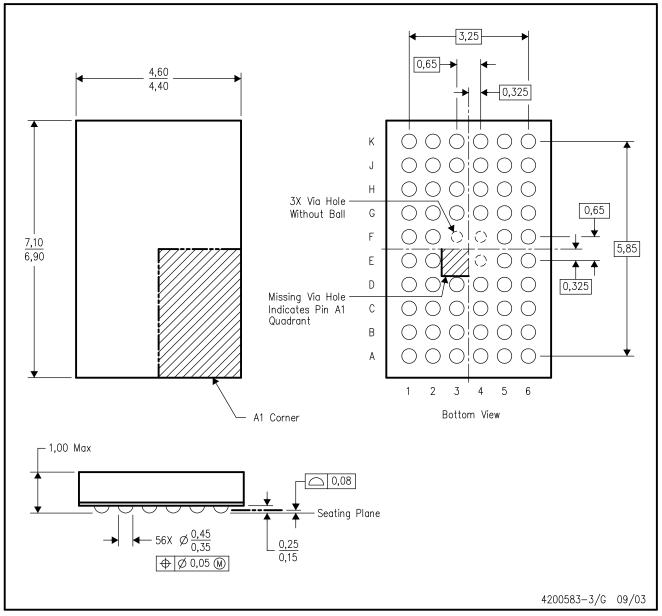
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. MicroStar Junior™ BGA configuration.
- D. Falls within JEDEC MO-225 variation BA.
- E. This package is lead-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).

MicroStar Junior is a trademark of Texas Instruments.



GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. MicroStar Junior™ BGA configuration.
- D. Falls within JEDEC MO-225 variation BA.
- E. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.

MicroStar Junior is a trademark of Texas Instruments.



DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

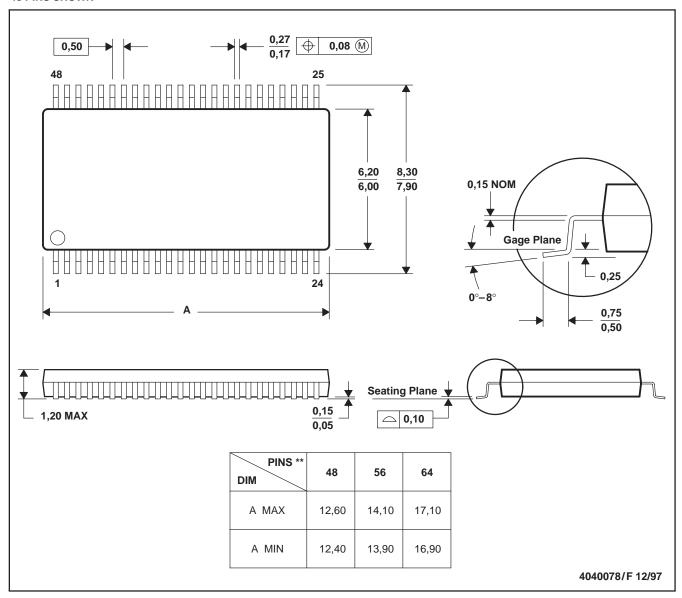
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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